



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moden et al.

Serial No.: 10/792,222

Filed: March 3, 2004

For: A METHOD FOR FORMING A LOW
PROFILE MULTI-IC CHIP PACKAGE
CONNECTOR (as amended)

Confirmation No.: 4777

Examiner: M. Trinh

Group Art Unit: 3729

Attorney Docket No.: 2269-3389.8US
(97-0638.08/US)

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AMENDMENT ACCOMPANYING REQUEST FOR CONTINUED EXAMINATION
(RCE)

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed April 14, 2006, and the Advisory Action mailed June 27, 2006, the three-month shortened statutory period for response to which expires on July 14, 2006.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.